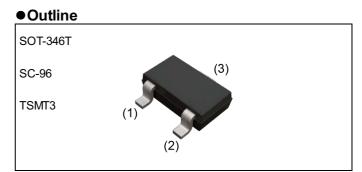


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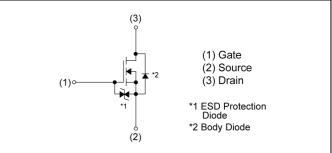
Nch 45V 2.5A Small Signal MOSFET

Datasheet

V _{DSS}	45V
R _{DS(on)} (Max.)	130mΩ
I _D	±2.5A
P _D	1.0W



Inner circuit



Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	180
Туре	Tape width (mm)	8
	Quantity (pcs)	3000
	Taping code	TL
	Marking	PW

• Absolute maximum ratings (T_a = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V _{DSS}	45	V
Continuous drain current	I _D	±2.5	A
Pulsed drain current	I _{DP} *1	±10	A
Gate - Source voltage	V _{GSS}	±12	V
Dower discipation	P _D *2	1.0	W
Power dissipation	P _D *3	0.7	W
Junction temperature	Tj	150	°C
Operating junction and storage temperature range	T _{stg}	-55 to +150	C°

Features
1) Low on-resistance
2) Built-in G-S protection diode
3) Small surface mount package(TSMT3)

Application

Switching

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•Thermal resistance

Deremeter	Sumbol	Values			Linit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal registeres innetion embient	R_{thJA}^{*2}	-	-	125	°C/W
Thermal resistance, junction - ambient	R_{thJA}^{*3}	-	-	178	°C/W

•Electrical characteristics (T_a = 25°C)

Deremeter	Currence of	Conditions	Values			1.1:4	
Parameter	Symbol Conditions		Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	xdown $V_{(BR)DSS}$ $V_{GS} = 0V, I_D = 1mA$		45	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_j}$	I _D = 1mA referenced to 25°C	-	46.8	-	mV/°C	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 45V, V _{GS} = 0V	-	-	1	μA	
Gate - Source leakage current	I _{GSS}	V_{GS} = ±12V, V_{DS} = 0V	-	-	±10	μA	
Gate threshold voltage	$V_{GS(th)}$	V _{DS} = 10V, I _D = 1mA	0.5	-	1.5	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_j}$	I _D = 1mA referenced to 25°C	-	-3.9	-	mV/°C	
		V _{GS} = 4.5V, I _D = 2.5A	-	95	130		
Static drain - source on - state resistance	R _{DS(on)} *4	V _{GS} = 4V, I _D = 2.5A	-	100	140	mΩ	
		V _{GS} = 2.5V, I _D = 2.5A	-	125	175		
Gate resistance	R _G	f = 1MHz, open drain	-	9.2	-	Ω	
Forward Transfer Admittance	Y _{fs} ^{*4}	V _{DS} = 10V, I _D = 2.5A	2.0	-	-	S	

*1 Pw \leq 10µs, Duty cycle \leq 1%

- *2 Mounted on a ceramic board (30x30x0.8mm)
- *3 Mounted on a FR4 (25x25x0.8mm)
- *4 Pulsed



• Electrical characteristics ($T_a = 25^{\circ}C$)

Deremeter	Sympol	Conditions	Values			Lloit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Input capacitance	C _{iss}	V _{GS} = 0V	-	250	-		
Output capacitance	C _{oss}	V _{DS} = 10V	-	60	-	pF	
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	30	-		
Turn - on delay time	$t_{d(on)}^{*4}$	$V_{DD} \simeq 25 V, V_{GS} = 4.5 V$	-	9	-		
Rise time	t _r *4	I _D = 1.2A	-	15	-		
Turn - off delay time	$t_{d(off)}^{*4}$	R _L ≃ 20.8Ω	-	20	-	ns	
Fall time	t _f *4	R _G = 10Ω	-	14	-		

• Gate charge characteristics (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit	
	Symbol Conditions		Min.	Тур.	Max.	Unit	
Total gate charge	Q_g^{*4}	V _{DD} ≃ 25V,	-	3.2	-		
Gate - Source charge	Q _{gs} *4	I _D = 2.5A,	-	0.9	-	nC	
Gate - Drain charge	${\sf Q}_{\sf gd}{}^{*4}$	V _{GS} = 4.5V	-	0.7	-		

•Body diode electrical characteristics (Source-Drain) ($T_a = 25^{\circ}C$)

Parameter	Symbol	Conditions	Values			Unit
Parameter Symbol		Conditions	Min.	Тур.	Max.	Unit
Continuous forward current	۱ _s	$T = 25^{\circ}$	-	-	0.8	А
Pulse forward current	I_{SP}^{*1}	T _a = 25°C	-	-	10	А
Forward voltage	V_{SD}^{*4}	V _{GS} = 0V, I _S = 2.5A	-	-	1.2	V



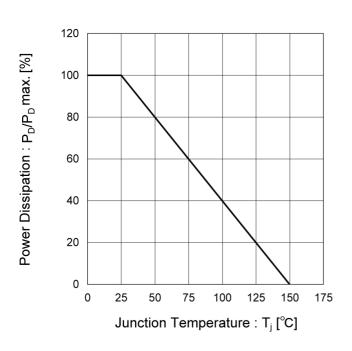


Fig.1 Power Dissipation Derating Curve

Fig.2 Maximum Safe Operating Area

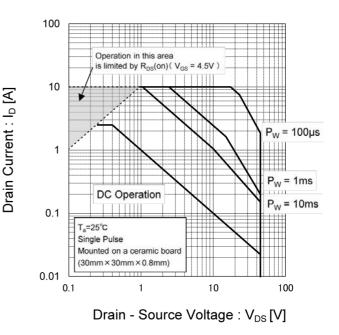


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

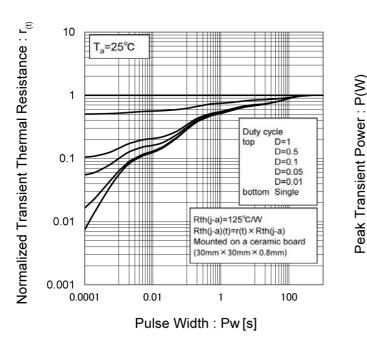
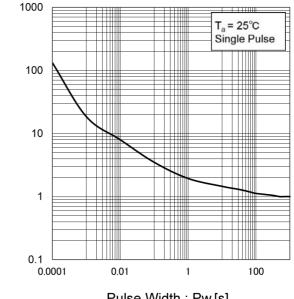


Fig.4 Single Pulse Maximum Power dissipation





• Electrical characteristic curves

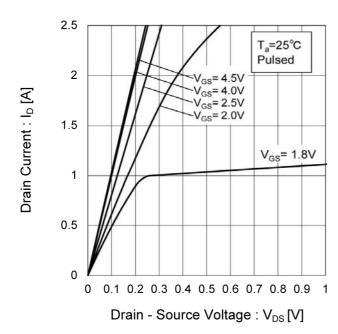


Fig.5 Typical Output Characteristics(I)

Fig.6 Typical Output Characteristics(II)

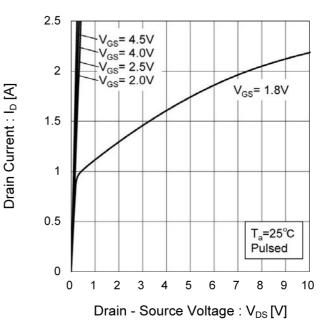
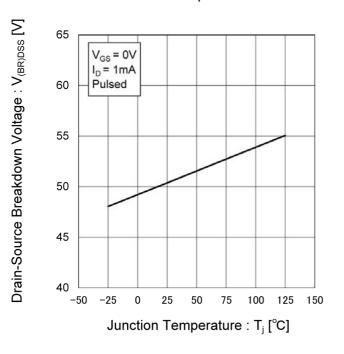


Fig.7 Breakdown Voltage vs. Junction Temperature





• Electrical characteristic curves

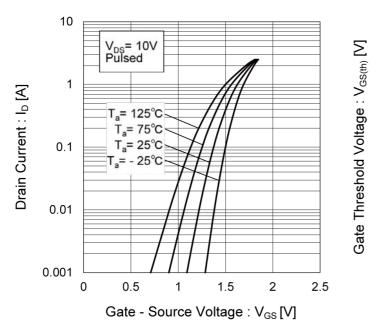


Fig.8 Typical Transfer Characteristics

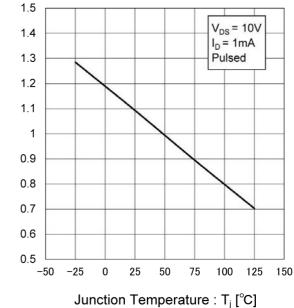
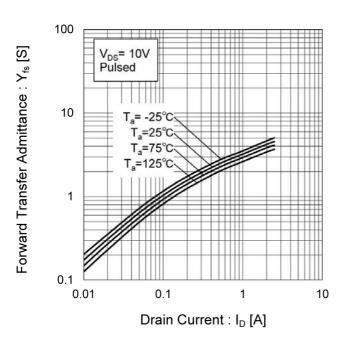


Fig.9 Gate Threshold Voltage vs. Junction Temperature

Fig.10 Forward Transfer Admittance vs. Drain Current







T_a=25°C

Pulsed

7 8 9 10

• Electrical characteristic curves

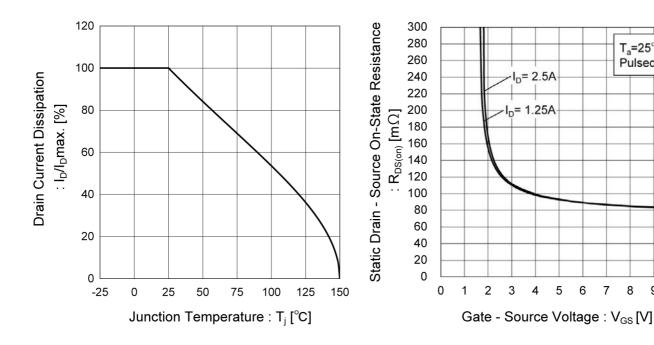
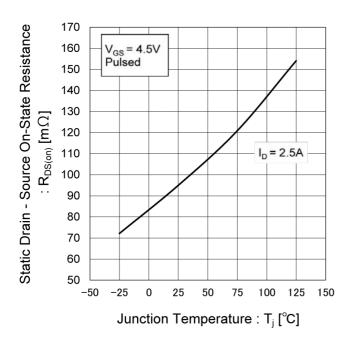


Fig.11 Drain Current Derating Curve

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature







Electrical characteristic curves

Fig.14 Static Drain - Source On - State

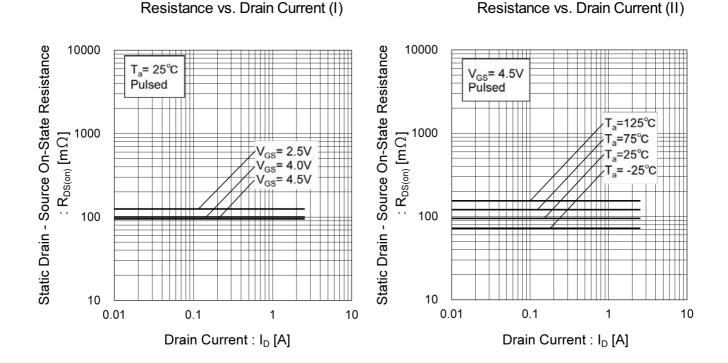
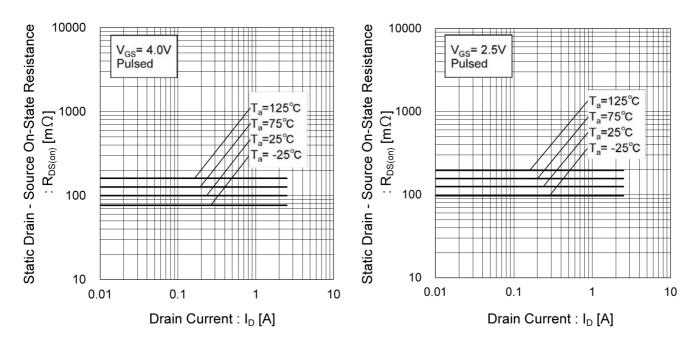


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III) Fig.17 Static Drain - Source On - State Resistance vs. Drain Current (IV)

Fig.15 Static Drain - Source On - State





• Electrical characteristic curves

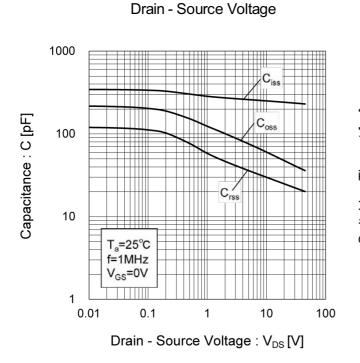


Fig.18 Typical Capacitance vs.

Fig.19 Switching Characteristics

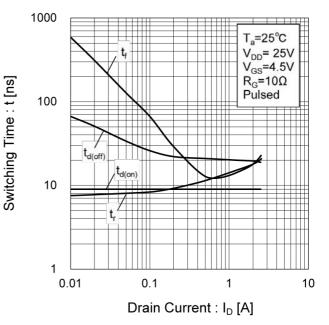
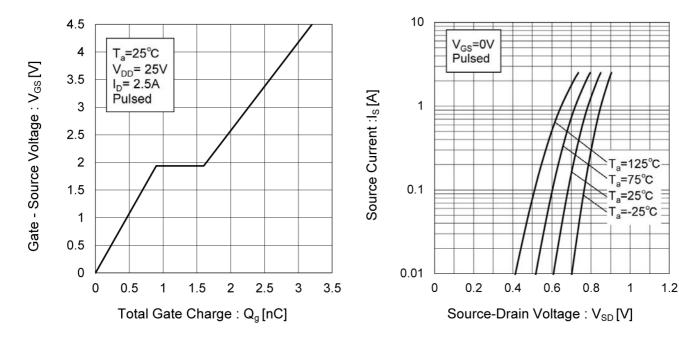


Fig.20 Dynamic Input Characteristics

Fig.21 Source Current vs. Source Drain Voltage





Measurement circuits



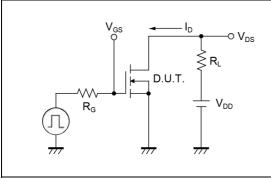


Fig.2-1 Gate Charge Measurement Circuit

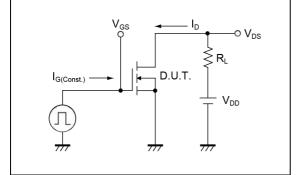


Fig.1-2 Switching Waveforms

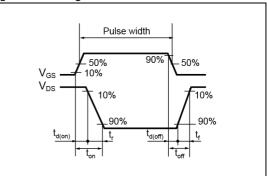
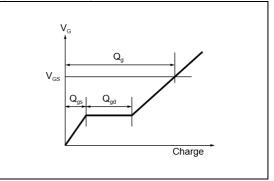


Fig.2-2 Gate Charge Waveform



Notice

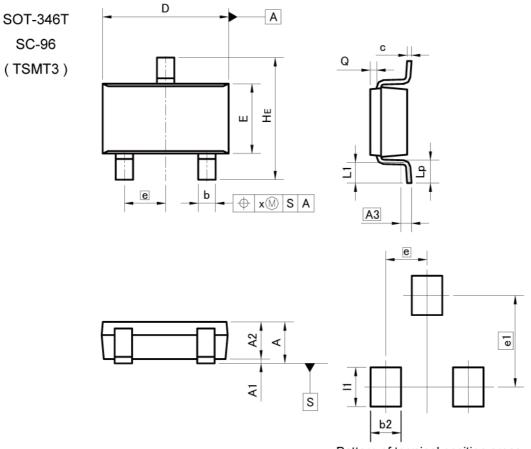
This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.





RQ5H025TN

Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM -	MILIM	ETERS	INC	HES
	MIN	MAX	MIN	MAX
A	E	1.00	-	0.039
A1	0.00	0.10	0.000	0.004
A2	0.75	0.95	0.030	0.037
A3	0.:	25	0.0	10
b	0.35	0.50	0.014	0.020
с	0.10	0.26	0.004	0.010
D	2.80	3.00	0.110	0.118
E	1.50	1.80	0.059	0.071
е	0.	95	0.0	37
HE	2.60	3.00	0.102	0.118
L1	0.30	0.60	0.012	0.024
Lp	0.40	0.70	0.016	0.028
Q	0.05	0.25	0.002	0.010
x	7.76	0.20		0.008

DIM	MILIMETERS		INC	HES
	MIN	MAX	MIN	MAX
b2		0.70	<u>57</u> .0	0.028
e1	2.1	0	0.0	083
11	7 %	0.90	1 7%	0.035

Dimension in mm/inches



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CLASSⅣ	CLASSⅢ	CLASSⅢ	CLASSII

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 - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
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 - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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When disposing Products please dispose them properly using an authorized industry waste company.

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